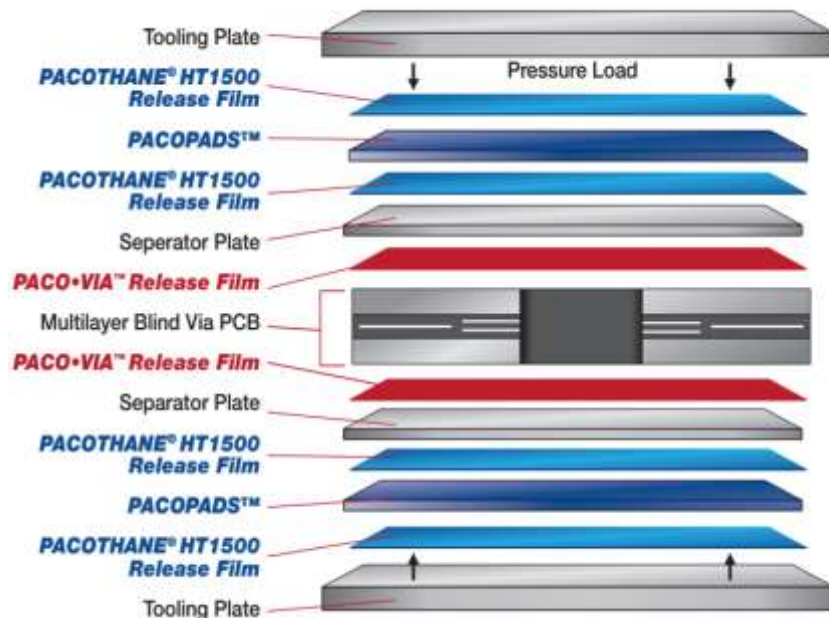


TECHNICAL DATA SHEET

PRODUCT:

PACOVIA 3500 is engineered to provide an easy and reliable technique for laminating multilayer Printed Circuit Boards, which incorporate **buried and blind via hole technology**. PACOVIA prevents blind via **resin overflow** and provides discreet control of liquid resin so that internal buried via hole barrels will be completely filled with easy release characteristics.

RECOMMENDED LAMINATION LAY-UP:



TECHNICAL DATA:

Physical Property		Test Method		Reported Units	Typical Values
Thickness		Q 3019		Mils/Microns	3.50/88
Density		ASTM		g/cm3	0.94
Flow		Q 1045		%	0.95 ≤ X ≤ 1.05
Max. Application Temp.		Q1025		°F/°C	425/218
Appearance		White-Translucent			
Tensile Strength (at Yield Point)	MD	YP	ASTM D882	Kg/Cm2	230
		Elong	ASTM D882	%	410
	TD	YP	ASTM D882	Kg/Cm2	190
		Elong	ASTM D882	%	520

Note: Pacothane generates this data sheet and specification that are just for reference. We cannot control the performance impact of different process and manufacturing variables.